



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

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Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



PNZ330CL (PN330CL)

Silicon planar type

For optical control systems

■ Features

- TO-18 standard type package
- High coupling capability suitable for plastic fiber
- High quantum efficiency
- High-speed response

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

| Parameter | Symbol | Rating | Unit |
|-------------------------------|-----------|-------------|------------------|
| Reverse voltage | V_R | 30 | V |
| Power dissipation | P_D | 100 | mW |
| Operating ambient temperature | T_{opr} | -25 to +85 | $^\circ\text{C}$ |
| Storage temperature | T_{stg} | -30 to +100 | $^\circ\text{C}$ |

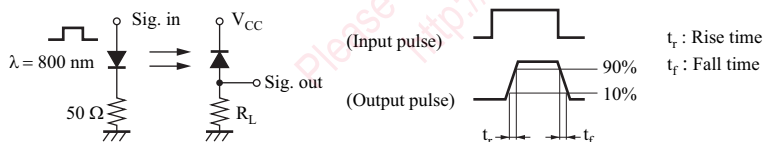
■ Electrical-Optical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

| Parameter | Symbol | Conditions | Min | Typ | Max | Unit |
|-----------------------------|----------------|--|-----|-----|-----|---------------|
| Photocurrent *1 | I_L | $V_R = 10\text{ V}, L = 1000\text{ lx}$ | 7 | 10 | | μA |
| Drain current | I_D | $V_R = 10\text{ V}$ | | 0.1 | 10 | nA |
| Terminal capacitance | C_t | $V_R = 0\text{ V}, f = 1\text{ MHz}$ | | 7 | | pF |
| Peak sensitivity wavelength | λ_{PD} | $V_R = 10\text{ V}$ | | 850 | | nm |
| Half-power angle | θ | The angle when the photocurrent is halved | | 70 | | $^\circ$ |
| Rise time *2 | t_r | $V_R = 10\text{ V}, R_L = 50\text{ k}\Omega$ | | 2 | | ns |
| Fall time *2 | t_f | | | 2 | | ns |

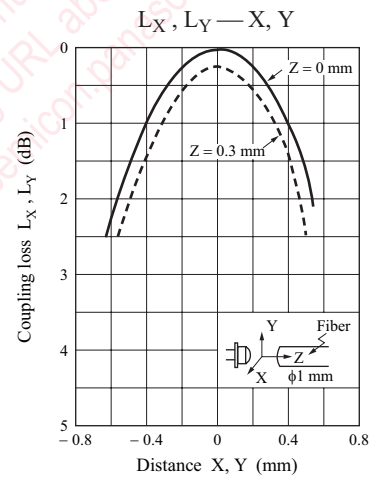
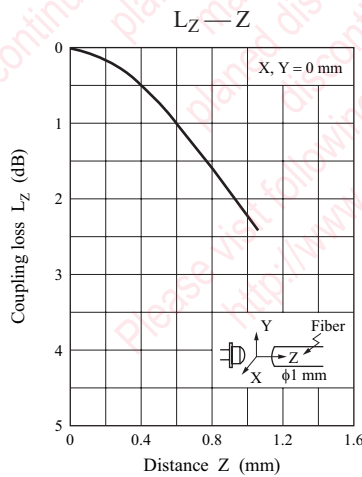
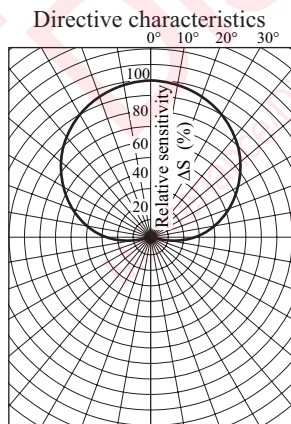
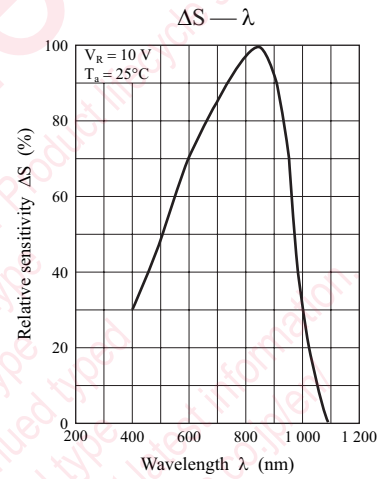
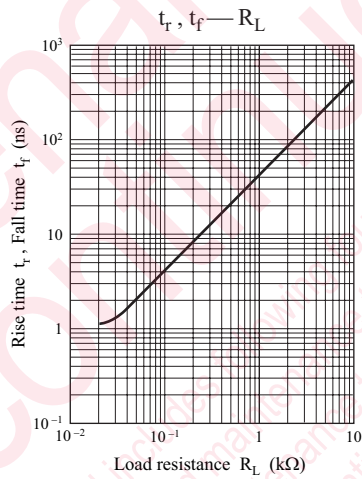
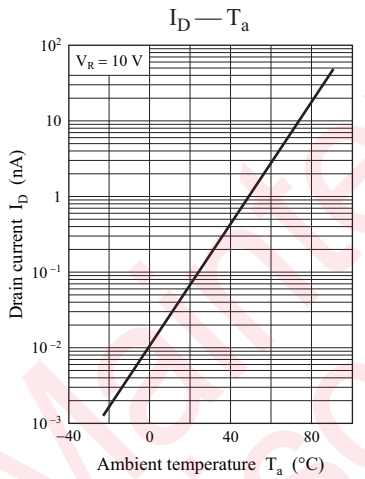
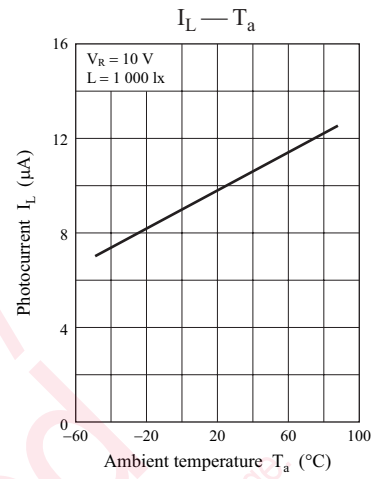
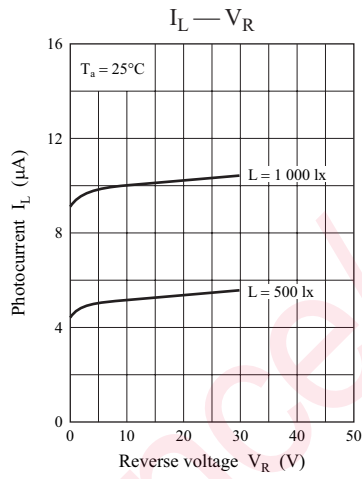
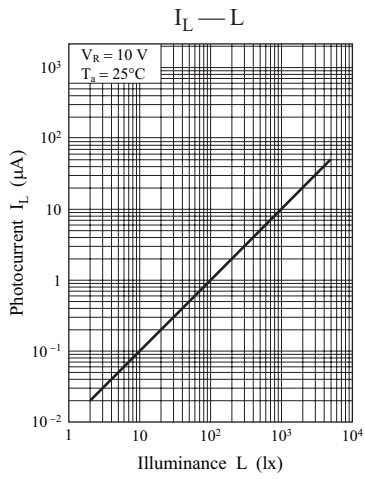
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

2. Spectral sensitivity characteristics: Sensitivity for wave length over 400 nm maximum sensitivity ratio is 100%.
3. This device is designed by disregarding radiation.
4. *1: Source: Tungsten lamp (color temperature 2 856K)

*2: Switching time measurement circuit

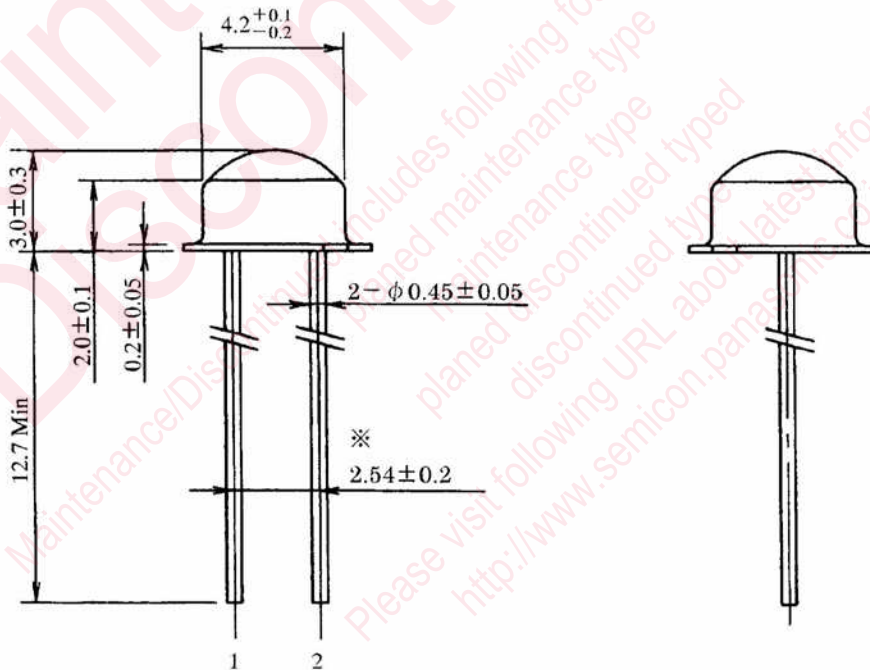
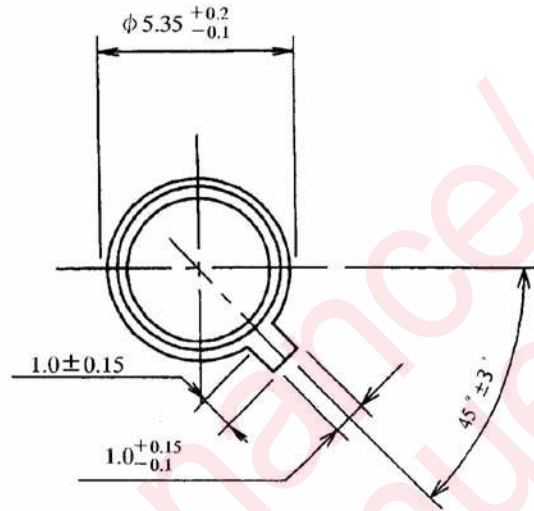


Note) The part number in the parenthesis shows conventional part number.



■ Package (Unit: mm)

MPDLTN2S0001



(注 1)(Note1)※リード根元寸法とする。／※Indicates root dimensions of lead.

- Pin name
- 1: Anode
- 2: Cathode

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